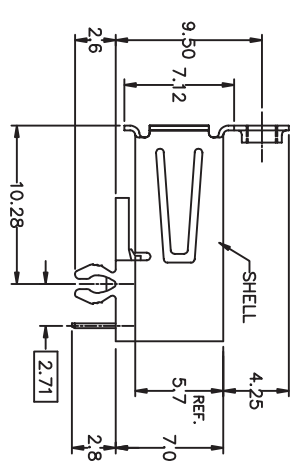
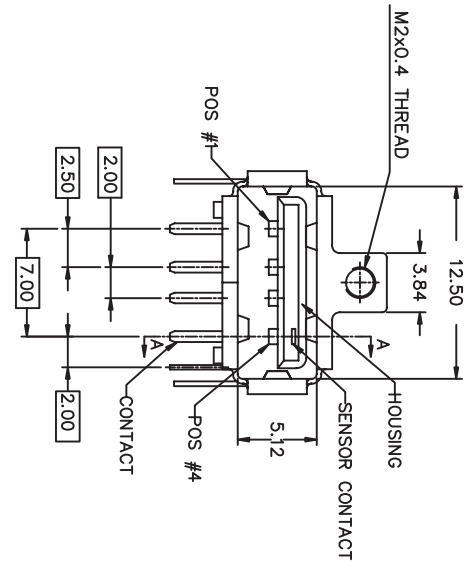
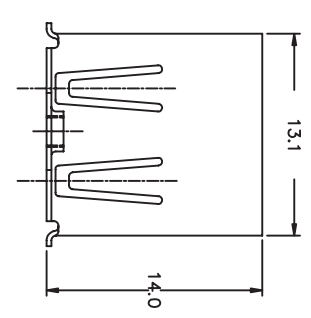
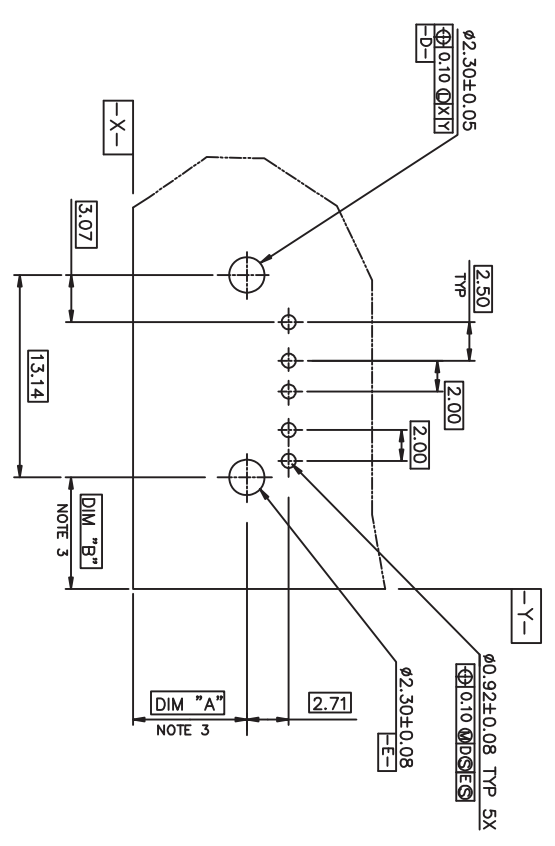


PRODUCT NO.  
SEE SHEET 3



ASSEMBLY WITHOUT BACK SHIELD



P.C. BOARD LAYOUT

rev.	ecn no.	dr.	date	tolerance unless otherwise specified	CUSTOMER COPY	title	product family	dwg no.	code
A	T70233	P P	6/18/97	.00 ± 0.30	UNIVERSAL BUS	RECEPTACLE-CATALOG			
B	T70333	C L	08/11/97	.0002 ± 0.10					
C	T04-0208	W L	05/13/04	± .3					
D	N04-0123	PH	12/13/04						
E	N06-0101	HB	04/13/08						

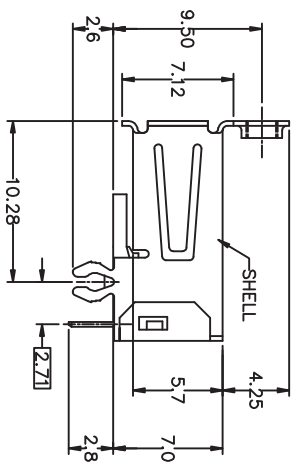
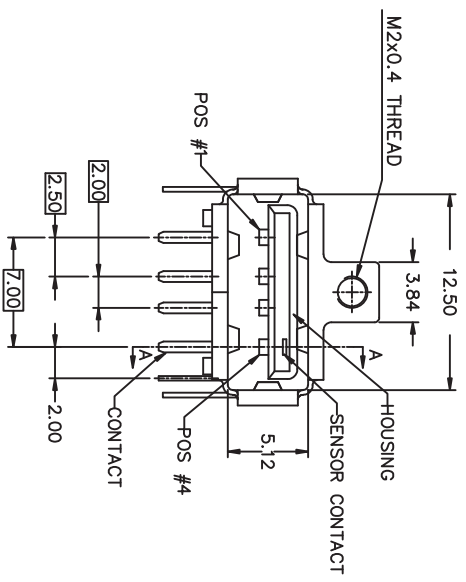
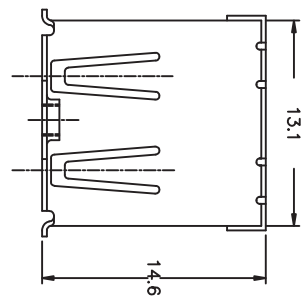
mat'l code	line ar	projec tion	unit	scale

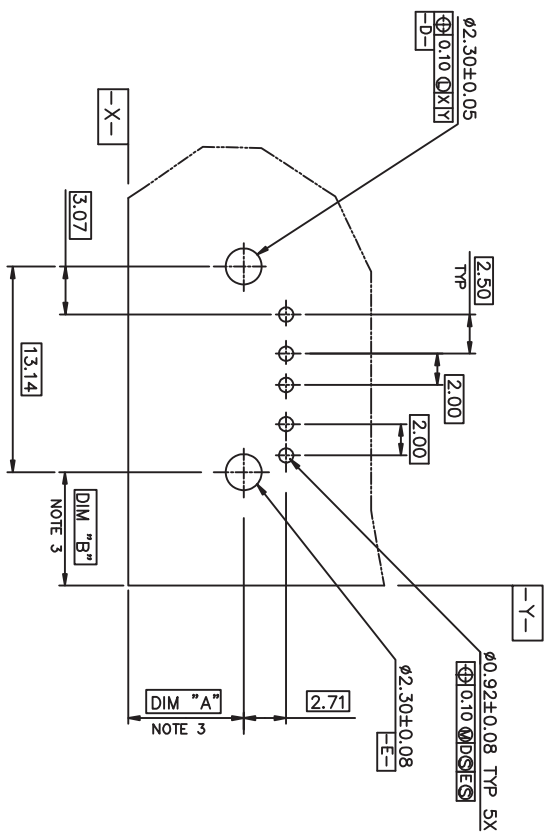
sheet revision	E	B	E
index sheet	1	2	3



PRODUCT NO.  
 SEE SHEET 3



ASSEMBLY WITH BACK SHIELD



P.C. BOARD LAYOUT

mat'l code	tolerance unless otherwise specified	CUSTOMER COPY	projection	title
rev. ecn no. dr. date	0 ± 0.30	COPY	1st angle	UNIV. SERIAL BUS S.M.T. RECEP-TACLE-CATALOG
B	.00 ± 0.20			Product family: USB
	.000 ± 0.10			dwg no. 61819
	± .3°			code
dir	SHIRLEY HSU dr/10/97			sheet
engr	R Y LIU dr/10/97			2 OF
chr	R Y LIU dr/10/97			
appd	JENN TSAO dr/10/97			
scale	2.5:1			
sheet revision				
index				

PRODUCT NUMBER CODE

61819 - X X X X X S LF

BASE PRODUCT NUMBER

HOUSING COLOR OPTIONS

- 0 - WHITE
- 1 - BLACK

PIN NO. OPTION

- 0 - 5 PIN
- 1 - 4 PIN

SHELL OPTIONS

- 1 - WITHOUT BACK SHIELD
- 2 - WITH BACK SHIELD

TERMINAL PLATING OPTION

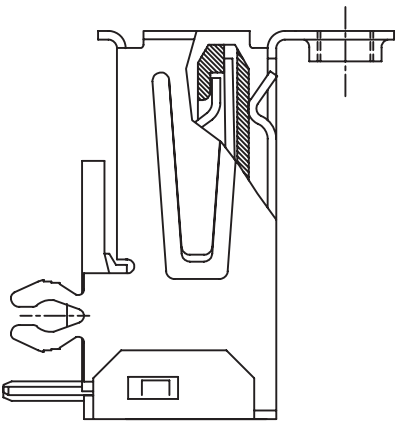
- 0 - 50u" Ni UNDERPLATE
- 30u" GXT CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 1 - 50u" Ni UNDERPLATE
- 30u" GXT CONTACT AREA
- 100u" TIN TAIL AREA

PACKAGING OPTION

- B - TUBES

ONLY FOR PANASONIC

LEAD FREE OPTION WHEN "TERMINAL PLATING OPTION" IS 1



NOTES:

1. MATERIAL: CONTACTS: PHOSPHOR BRONZE SHIELD: PHOSPHOR BRONZE HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: WHITE
2. PLATING: CONTACTS: GOLD FLASH OVER PALLADIUM NICKEL (0.76um MINIMUM) IN CONTACT AREA; 2.54 um TIN-LEAD OR TIN MINIMUM IN SOLDER TAIL AREA. 1.27 um MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES. SHIELD: 2.54 um MINIMUM TIN/LEAD OR TIN OVER 1.27 um MINIMUM NICKEL UNDERPLATE
3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER.
4. RECOMMENDED BOARD THICKNESS IS 0.8~1.2 mm.
5. MAXIMUM PANEL THICKNESS TO BE 2.67 mm IF MOUNTED BEHIND PANEL.
6. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
7. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008
8. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR PHASE REFLOW OVEN.

mat'l code	tolerance unless otherwise specified	CUSTOMER COPY	projection	title	product family	code
rev. ecn no. dr. date	linear			UNIV. SERIAL BUS RECEPTACLE		
E	0 ± 0.30					
	.00 ± 0.20					
	.000 ± 0.10					
	angles ± .3°					
	dir. SHIPLEY HSJ01/10/97					
	engr. R Y LUU 01/10/97					
	chr. R Y LUU 01/10/97					
	appd. JENN TSAO 01/10/97					
sheet revision						
index sheet						

